

Exhibit 1

#	Claim Term(s), Phrase(s), or Clause(s)	HID's Evidence	Samsung's Evidence
1	“disposed in at least one corner of a semiconductor substrate” ’826 Patent Claims 1, 11	<u>Intrinsic Evidence:</u> Abstract, Figs. 1A-3C; 1:14-46; 4:7-36; 5:62-6:46; 6:53-7:41. <u>Extrinsic Evidence:</u> Lei et al., “Die Singulation Technologies for Advanced Packaging: A Critical Review” Zhang et al., “3D Fracture Mechanics Analysis of Underfill Delamination for Flip Chip Packages” Ho et al., “3D vs 2D Modeling of the Effect of Die Size on Delamination in Encapsulated IC Packages” Chin et al., “Reliability Evaluation Methodology for Chip-Package Interaction – Die Corner Edge Failure Mechanism” Rabie et al., “Optimizing Die Corner and Optical Groove Corner Crackstop Support	<u>Intrinsic Evidence:</u> Abstract, 1:30-38, 1:42-46, 2:44-3:11, 4:7-7:33, 7:59-60, 8:9-20, 8:35-36, 8:53-64, Figs. 1A, 2A-2D, 3A-3E. IPR2024-01405, Patent Owner’s Preliminary Response (December 30, 2024) at, e.g., 21. <u>Extrinsic Evidence:</u> Expert Declaration of Dr. Dean Neikirk at ¶¶ 45-51.

